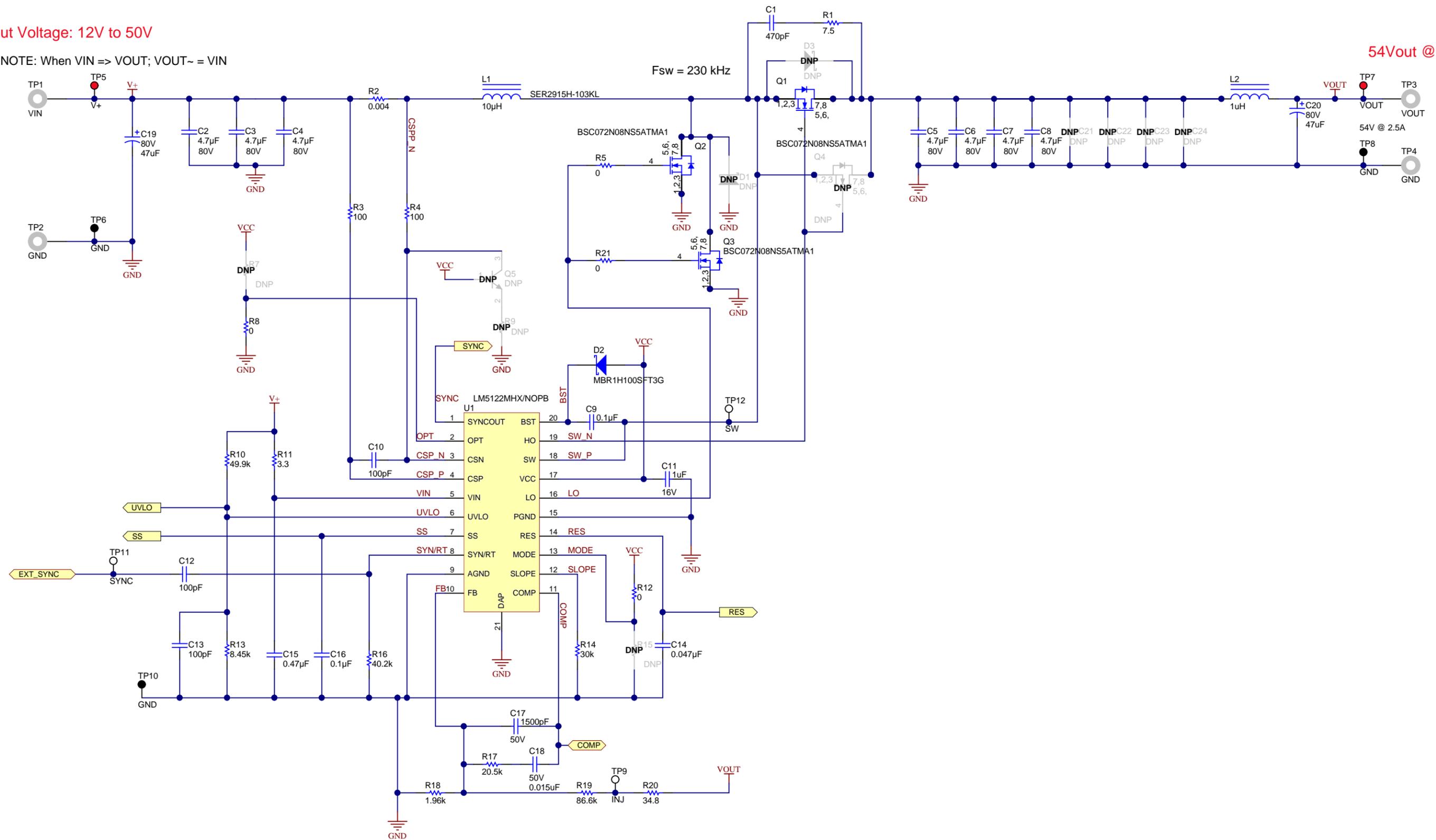


Input Voltage: 12V to 50V

NOTE: When VIN => VOUT; VOUT~ = VIN

54Vout @ 2.5A

Fsw = 230 kHz



Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 11/29/2017
TID #: PMP21274	Project Title: LM5122 Boost	
Number: PMP21274	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP21274_REVA.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	



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H1 NY PMS 440 0025 PH
 H2 NY PMS 440 0025 PH
 H3 NY PMS 440 0025 PH
 H4 NY PMS 440 0025 PH

H5 1902C
 H6 1902C
 H7 1902C
 H8 1902C

DNP FID1
 DNP FID2
 DNP FID3

PCB Number: PMP21274
 PCB Rev: A

Variant/Label Table	
Variant	Label Text
001	

ZZ1
 Label Assembly Note
 This Assembly Note is for PCB labels only

ZZ2
 Assembly Note
 This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
 Assembly Note
 This Assembly Note will show in the PcbDoc and associated outputs

ZZ4
 Assembly Note
 This Assembly Note will show in the PcbDoc and associated outputs

Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 11/15/2017
TID #: PMP21274	Project Title: LM5122 Boost	
Number: PMP21274	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: PMP21274_REVA_Hardware.SchDoc	Size: B
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	

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